

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L60	1	"324"/\$ and strip with (die dice) with ((locat\$4 position) and ((database data adj base) (camera vision)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 15:36
L59	35	"324"/\$ and strip with (die dice) with ((locat\$4 position) (database data adj base) (camera vision))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 15:36
L48	10	"700"/\$ and strip with (die dice) with ((locat\$4 position) (database data adj base) (camera vision))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 15:33
L57	5	strip with (die dice) same ((locat\$4 position) and ((database data adj base) and (camera vision)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 14:37
L56	9	strip with (die dice) with ((locat\$4 position) and ((database data adj base) (camera vision)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 14:37
L47	2157	strip with (die dice) with ((locat\$4 position) (database data adj base) (camera vision))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 14:06
L55	141	"257"/\$ and strip with (die dice) with ((locat\$4 position) (database data adj base) (camera vision))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 14:02
L54	24	"235"/\$ and strip with (die dice) with ((locat\$4 position) (database data adj base) (camera vision))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 14:02
L53	278	"156"/\$ and strip with (die dice) with ((locat\$4 position) (database data adj base) (camera vision))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 14:02
L52	79	"438"/\$ and strip with (die dice) with ((locat\$4 position) (database data adj base) (camera vision))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 14:02

L51	0	"716"/\$ and strip with (die dice) with ((locat\$4 position) (database data adj base) (camera vision))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 14:02
L50	0	"714"/\$ and strip with (die dice) with ((locat\$4 position) (database data adj base) (camera vision))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 14:02
L49	3	"702"/\$ and strip with (die dice) with ((locat\$4 position) (database data adj base) (camera vision))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 14:02
L45	5	strip with (die dice) same ((locat\$4 position) and (database data adj base) and (camera vision))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 14:01
L44	9	strip with (die dice) same ((locat\$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:52
L43	20	strip same (die dice) same ((locat\$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:39
L42	5	strip with (die dice) with ((locat\$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:37
L41	4	(camera vision) and strip with (die dice) with ((locat\$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:36
L40	3	"438"/\$ and (camera vision) and strip with (die dice) with ((locat\$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:35
L39	2	"257"/\$ and (camera vision) and strip with (die dice) with ((locat\$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:34

L38	0	"235"/\$ and (camera vision) and strip with (die dice) with ((locat\$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:34
L37	3	"156"/\$ and (camera vision) and strip with (die dice) with ((locat\$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:34
L36	0	"716"/\$ and (camera vision) and strip with (die dice) with ((locat\$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:34
L35	0	"702"/\$ and (camera vision) and strip with (die dice) with ((locat\$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:34
L34	1	"700"/\$ and (camera vision) and strip with (die dice) with ((locat\$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:34
L33	0	"714"/\$ and (camera vision) and strip with (die dice) with ((locat\$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:34
L28	2	"714"/\$ and (camera vision) and (strip die dice) with ((locat\$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:33
L32	5	"235"/\$ and (camera vision) and (strip die dice) with ((locat\$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:32
L31	4	"257"/\$ and (camera vision) and (strip die dice) with ((locat\$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:32
L30	6	"156"/\$ and (camera vision) and (strip die dice) with ((locat\$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:32

L29	3	"716"/\$ and (camera vision) and (strip die dice) with ((locat\$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:32
L27	5	"702"/\$ and (camera vision) and (strip die dice) with ((locat\$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:31
L26	4	"700"/\$ and (camera vision) and (strip die dice) with ((locat\$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:31
L25	16	"438"/\$ and (camera vision) and (strip die dice) with ((locat\$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:31
L24	3	"438"/\$ and (camera vision) and wafer same strip same (die dice) and (strip die dice) with ((locat\$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:31
L23	2	"257"/\$ and (camera vision) and wafer same strip same (die dice) and (strip die dice) with ((locat\$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:31
L21	3	"156"/\$ and (camera vision) and wafer same strip same (die dice) and (strip die dice) with ((locat\$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:31
L22	0	"235"/\$ and (camera vision) and wafer same strip same (die dice) and (strip die dice) with ((locat\$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:30
L20	0	"716"/\$ and (camera vision) and wafer same strip same (die dice) and (strip die dice) with ((locat\$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:30
L19	0	"714"/\$ and (camera vision) and wafer same strip same (die dice) and (strip die dice) with ((locat\$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:30

L18	0	"702"/\$ and (camera vision) and wafer same strip same (die dice) and (strip die dice) with ((locat\$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:30
L17	1	"700"/\$ and (camera vision) and wafer same strip same (die dice) and (strip die dice) with ((locat\$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:29
L16	19	(camera vision) and wafer same strip same (die dice) and (strip die dice) with ((locat\$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:28
L15	15	(camera vision) and wafer same strip same (die dice) and (strip die dice) with ((locat\$4 position) and (database data adj base)) and (@ad<"20010227" @rlad<"20010227")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:28
L14	4	wafer with strip with (die dice) and (strip die dice) with ((locat\$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:17
L13	0	wafer with strip with (die dice) and (strip die dice) with ((locat\$4 position) and (database data adj base)) and (@ad<"20010227" @rlad<"20010227")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:17
L11	0	(camera vision) and wafer with strip with (die dice) and (strip die dice) with ((locat\$4 position) and (database data adj base)) and (@ad<"20010227" @rlad<"20010227")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:17
L12	4	(camera vision) and wafer with strip with (die dice) and (strip die dice) with ((locat\$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:16
L10	51	(camera vision) and wafer with strip die dice) and (strip die dice) with ((locat\$4 position) and (database data adj base)) and (@ad<"20010227" @rlad<"20010227")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:15

L9	53	(camera vision) and wafer same (strip die dice) and (strip die dice) with ((locat\$4 position) and (database data adj base)) and (@ad<"20010227" @rlad<"20010227")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:13
L8	138	wafer same (strip die dice) and (strip die dice) with ((locat\$4 position) and (database data adj base)) and (@ad<"20010227" @rlad<"20010227")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:12
L7	17	wafer same strip same (die dice) and (strip die dice) with ((locat\$4 position) and (database data adj base)) and (@ad<"20010227" @rlad<"20010227")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:03
L6	21	wafer same strip same (die dice) and (strip die dice) with ((locat\$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 12:50
L5	34	wafer same strip same (die dice) and (wafer strip die dice) with ((locat\$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 12:43
L4	56	wafer same strip same die and (locat\$4 position) and (database data adj base)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 12:23
L3	605	wafer and strip and die and (locat\$4 position) and (database data adj base)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 12:21

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6049624 65
6226394 65
6226394 65
6400840 65
6730532 65
6730545 65
6901984 65
6931298 65
5549716 54
5726920 54
6100590 54
5220724 54
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5866948 54
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6117709 54
6194739 54
6230569 54
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4994736 54
5296738 54
5301143 54
5371943 54
5420460 54
5423119 54
5429992 54
5458158 54
5521430 54
5610437 54
5623123 54
5625631 54
5633528 54
5675127 54
5763057 54
5764577 54
5824964 54
5838023 54
5886362 54
5915231 54
5933713 54
5956838 54
5960260 54
6008061 54
6014018 54
6031281 54
6031724 54
6031784 54
6052287 54

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Titles of Most Frequently Occurring Classifications of Patents Returned
From A Search of 10086051 on November 03, 2005

6 257/676 (1 OR, 5 XR)
Class 257 : ACTIVE SOLID-STATE DEVICES
257/666 LEAD FRAME
257/676 .with structure for mounting semiconductor chip
to lead frame (e.g., configuration of die bonding flag,
absence of a die bonding flag, recess for LED)

6 257/E23.179 (0 OR, 6 XR)
Class 257 : ACTIVE SOLID-STATE DEVICES
257/E23.176 ...For flat cards, e.g., credit cards (EPO)
257/E23.179 .Marks applied to semiconductor devices or
parts, e.g., registration marks, test patterns, alignment
structures, wafer maps (EPO)

5 29/827 (2 OR, 3 XR)
Class 029 : METAL WORKING
29/592 METHOD OF MECHANICAL MANUFACTURE
29/592.1 .Electrical device making
29/825 ..Conductor or circuit manufacturing
29/827 ...Beam lead frame or beam lead device

5 257/666 (2 OR, 3 XR)
Class 257 : ACTIVE SOLID-STATE DEVICES
257/666 LEAD FRAME

5 257/778 (2 OR, 3 XR)
Class 257 : ACTIVE SOLID-STATE DEVICES
257/734 COMBINED WITH ELECTRICAL CONTACT OR LEAD
257/778 .Flip chip

5 257/E23.037 (0 OR, 5 XR)
Class 257 : ACTIVE SOLID-STATE DEVICES
257/E23.001 PACKAGING, INTERCONNECTS, AND MARKINGS FOR
SEMICONDUCTOR OR OTHER SOLID-STATE DEVICES (EPO)
257/E23.01 .Arrangements for conducting electric current
to or from solid-state body in operation, e.g., leads,
terminal arrangements (EPO)
257/E23.023 ..Consisting of soldered or bonded
constructions (EPO)
257/E23.031 ...Lead frames or other flat leads (EPO)
257/E23.037Characterized by die pad (EPO)

4 257/48 (4 OR, 0 XR)
Class 257 : ACTIVE SOLID-STATE DEVICES
257/48 TEST OR CALIBRATION STRUCTURE

4 382/145 (4 OR, 0 XR)
Class 382 : IMAGE ANALYSIS
382/100 APPLICATIONS
382/141 .Manufacturing or product inspection
382/145 ..Inspection of semiconductor device or printed
circuit board

4 702/187 (0 OR, 4 XR)
Class 702 : DATA PROCESSING: MEASURING, CALIBRATING, OR
TESTING
702/127 MEASUREMENT SYSTEM
702/187 .History logging or time stamping

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3 257/787 (0 OR, 3 XR)
Class 257 : ACTIVE SOLID-STATE DEVICES
257/787 ENCAPSULATED

3 257/E23.004 (0 OR, 3 XR)
Class 257 : ACTIVE SOLID-STATE DEVICES
257/E23.001 PACKAGING, INTERCONNECTS, AND MARKINGS FOR
SEMICONDUCTOR OR OTHER SOLID-STATE DEVICES (EPO)
257/E23.003 .Mountings, e.g., nondetachable insulating
substrates (EPO)
257/E23.004 ..Characterized by shape (EPO)

3 257/E23.043 (0 OR, 3 XR)
Class 257 : ACTIVE SOLID-STATE DEVICES
257/E23.001 PACKAGING, INTERCONNECTS, AND MARKINGS FOR
SEMICONDUCTOR OR OTHER SOLID-STATE DEVICES (EPO)
257/E23.01 .Arrangements for conducting electric current
to or from solid-state body in operation, e.g., leads,
terminal arrangements (EPO)
257/E23.023 ..Consisting of soldered or bonded
constructions (EPO)
257/E23.031 ...Lead frames or other flat leads (EPO)
257/E23.043Geometry of lead frame (EPO)

3 257/E23.067 (0 OR, 3 XR)
Class 257 : ACTIVE SOLID-STATE DEVICES
257/E23.001 PACKAGING, INTERCONNECTS, AND MARKINGS FOR
SEMICONDUCTOR OR OTHER SOLID-STATE DEVICES (EPO)
257/E23.01 .Arrangements for conducting electric current
to or from solid-state body in operation, e.g., leads,
terminal arrangements (EPO)
257/E23.023 ..Consisting of soldered or bonded
constructions (EPO)
257/E23.06 .Leads, i.e., metallizations or lead frames
on insulating substrates, e.g., chip carriers (EPO)
257/E23.067Via connections through substrates, e.g.,
pins going through substrate, coaxial cables (EPO)

3 438/123 (0 OR, 3 XR)
Class 438 : SEMICONDUCTOR DEVICE MANUFACTURING: PROCESS
438/106 PACKAGING (E.G., WITH MOUNTING, ENCAPSULATING,
ETC.) OR TREATMENT OF PACKAGED SEMICONDUCTOR
438/121 .Metallic housing or support
438/123 ..Lead frame

3 438/14 (0 OR, 3 XR)
Class 438 : SEMICONDUCTOR DEVICE MANUFACTURING: PROCESS
438/14 WITH MEASURING OR TESTING

3 438/18 (1 OR, 2 XR)
Class 438 : SEMICONDUCTOR DEVICE MANUFACTURING: PROCESS
438/14 WITH MEASURING OR TESTING
438/17 .Electrical characteristic sensed
438/18 ..Utilizing integral test element

2 29/566.3 (1 OR, 1 XR)
Class 029 : METAL WORKING
29/33R PLURAL DIVERSE MANUFACTURING APPARATUS
INCLUDING MEANS FOR METAL SHAPING OR ASSEMBLING
29/566 .Including composite tool

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29/566.1 ..Including severing means
 29/566.3 ...To trim electric component

2 29/740 (0 OR, 2 XR)
 Class 029 : METAL WORKING
 29/700 MEANS TO ASSEMBLE OR DISASSEMBLE
 29/729 .Means to assemble electrical device
 29/739 ..Means to fasten electrical component to
 wiring board, base, or substrate
 29/740 ...Chip component

2 29/840 (1 OR, 1 XR)
 Class 029 : METAL WORKING
 29/592 METHOD OF MECHANICAL MANUFACTURE
 29/592.1 .Electrical device making
 29/825 ..Conductor or circuit manufacturing
 29/829 ...On flat or curved insulated base, e.g.,
 printed circuit, etc.
 29/832Assembling to base an electrical component,
 e.g., capacitor, etc.
 29/840By metal fusion

2 29/841 (1 OR, 1 XR)
 Class 029 : METAL WORKING
 29/592 METHOD OF MECHANICAL MANUFACTURE
 29/592.1 .Electrical device making
 29/825 ..Conductor or circuit manufacturing
 29/829 ...On flat or curved insulated base, e.g.,
 printed circuit, etc.
 29/832Assembling to base an electrical component,
 e.g., capacitor, etc.
 29/841With encapsulating, e.g., potting, etc.

2 156/64 (1 OR, 1 XR)
 Class 156 : ADHESIVE BONDING AND MISCELLANEOUS CHEMICAL
 MANUFACTURE
 156/1 METHODS
 156/60 .Surface bonding and/or assembly therefor
 156/64 ..With measuring, testing, or inspecting

2 174/52.2 (1 OR, 1 XR)
 Class 174 : ELECTRICITY: CONDUCTORS AND INSULATORS
 174/50 BOXES AND HOUSINGS
 174/52.1 .With electric device or mounting means
 therefor
 174/52.2 ..Potted or encapsulated

2 257/673 (0 OR, 2 XR)
 Class 257 : ACTIVE SOLID-STATE DEVICES
 257/666 LEAD FRAME
 257/673 .With bumps on ends of lead fingers to connect
 to semiconductor

2 257/737 (0 OR, 2 XR)
 Class 257 : ACTIVE SOLID-STATE DEVICES
 257/734 COMBINED WITH ELECTRICAL CONTACT OR LEAD
 257/737 .Bump leads

2 257/758 (1 OR, 1 XR)
 Class 257 : ACTIVE SOLID-STATE DEVICES
 257/734 COMBINED WITH ELECTRICAL CONTACT OR LEAD
 257/741 .Of specified material other than unalloyed
 aluminum

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257/750

..Layered

257/758

...Multiple metal levels on semiconductor,
separated by insulating layer (e.g., multiple level
metallization for integrated circuit)

2 257/E21.505 (0 OR, 2 XR)

Class 257 : ACTIVE SOLID-STATE DEVICES

257/E21.001 PROCESSES OR APPARATUS ADAPTED FOR MANUFACTURE
OR TREATMENT OF SEMICONDUCTOR OR SOLID-STATE DEVICES

OR OF

257/E21.002 .Manufacture or treatment of semiconductor

device (EPO)

257/E21.04

..Device having at least one potential-jump
barrier or surface barrier, e.g., PN junction,

depletion

layer, carrier concentration layer (EPO)

257/E21.499

...Assembling semiconductor devices, e.g.,
packaging, including mounting, encapsulating, or

treatment

of packaged semiconductor (EPO)

257/E21.505

....Insulative mounting semiconductor device on
support (EPO)

2 257/E21.525 (0 OR, 2 XR)

Class 257 : ACTIVE SOLID-STATE DEVICES

257/E21.515Involving use of mechanical auxiliary part
without use of alloying or soldering process, e.g.,
pressure contacts (EPO)

257/E21.521

.Testing or measuring during manufacture or
treatment or reliability measurement, i.e., testing of
parts followed by no processing which modifies parts as
such (EPO)

257/E21.525

..Procedures, i.e., sequence of activities
consisting of plurality of measurement and correction,
marking or sorting steps (EPO)

2 257/E23.038 (0 OR, 2 XR)

Class 257 : ACTIVE SOLID-STATE DEVICES

257/E23.001 PACKAGING, INTERCONNECTS, AND MARKINGS FOR
SEMICONDUCTOR OR OTHER SOLID-STATE DEVICES (EPO)

257/E23.01

.Arrangements for conducting electric current
to or from solid-state body in operation, e.g.,

leads,

terminal arrangements (EPO)

257/E23.023

..Consisting of soldered or bonded
constructions (EPO)

257/E23.031

...Lead frames or other flat leads (EPO)

257/E23.037

....Characterized by die pad (EPO)

257/E23.038

.....Insulative substrate being used as die
pad, e.g., ceramic, plastic (EPO)

2 257/E23.046 (0 OR, 2 XR)

Class 257 : ACTIVE SOLID-STATE DEVICES

257/E23.001 PACKAGING, INTERCONNECTS, AND MARKINGS FOR
SEMICONDUCTOR OR OTHER SOLID-STATE DEVICES (EPO)

257/E23.01

.Arrangements for conducting electric current
to or from solid-state body in operation, e.g.,

leads,

terminal arrangements (EPO)

257/E23.023

..Consisting of soldered or bonded
constructions (EPO)

257/E23.031

...Lead frames or other flat leads (EPO)

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257/E23.043Geometry of lead frame (EPO)
257/E23.046Cross-section geometry (EPO)

2 257/E23.068 (0 OR, 2 XR)

Class 257 : ACTIVE SOLID-STATE DEVICES

257/E23.001 PACKAGING, INTERCONNECTS, AND MARKINGS FOR
SEMICONDUCTOR OR OTHER SOLID-STATE DEVICES (EPO)

257/E23.01 .Arrangements for conducting electric current
to or from solid-state body in operation, e.g., leads,
terminal arrangements (EPO)

257/E23.023 ..Consisting of soldered or bonded
constructions (EPO)

257/E23.06 ...Leads, i.e., metallizations or lead frames
on insulating substrates, e.g., chip carriers (EPO)

257/E23.068Additional leads joined to metallizations
on insulating substrate, e.g., pins, bumps, wires, flat
leads (EPO)

2 257/E23.125 (0 OR, 2 XR)

Class 257 : ACTIVE SOLID-STATE DEVICES

257/E23.113Ceramic materials or glass (EPO)

257/E23.116 .Encapsulations, e.g., encapsulating layers,
coatings, e.g., for protection (EPO)

257/E23.123 ..Characterized by arrangement or shape (EPO)

257/E23.124 ...Device being completely enclosed (EPO)

257/E23.125Substrate forming part of encapsulation
(EPO)

2 324/73.1 (0 OR, 2 XR)

Class 324 : ELECTRICITY: MEASURING AND TESTING

324/73.1 PLURAL, AUTOMATICALLY SEQUENTIAL TESTS

2 324/765 (1 OR, 1 XR)

Class 324 : ELECTRICITY: MEASURING AND TESTING

324/500 FAULT DETECTING IN ELECTRIC CIRCUITS AND OF
ELECTRIC COMPONENTS

324/537 .of individual circuit component or element

324/765 ..Test of semiconductor device

2 361/764 (0 OR, 2 XR)

Class 361 : ELECTRICITY: ELECTRICAL SYSTEMS AND DEVICES

361/600 HOUSING OR MOUNTING ASSEMBLIES WITH DIVERSE
ELECTRICAL COMPONENTS

361/679 .For electronic systems and devices

361/748 ..Printed circuit board

361/760 ...Connection of components to board

361/761Component within printed circuit board

361/764Integrated circuit

2 438/106 (0 OR, 2 XR)

Class 438 : SEMICONDUCTOR DEVICE MANUFACTURING: PROCESS

438/106 PACKAGING (E.G., WITH MOUNTING, ENCAPSULATING,
ETC.) OR TREATMENT OF PACKAGED SEMICONDUCTOR

2 438/613 (0 OR, 2 XR)

Class 438 : SEMICONDUCTOR DEVICE MANUFACTURING: PROCESS

438/584 COATING WITH ELECTRICALLY OR THERMALLY
CONDUCTIVE MATERIAL

438/597 .To form ohmic contact to semiconductive

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material

438/612 ..Forming solder contact or bonding pad
438/613 ...Bump electrode

2 438/622 (0 OR, 2 XR)

Class 438 : SEMICONDUCTOR DEVICE MANUFACTURING: PROCESS

438/584 COATING WITH ELECTRICALLY OR THERMALLY
CONDUCTIVE MATERIAL

438/597 .To form ohmic contact to semiconductive
material

438/618 ..Contacting multiple semiconductive regions
(i.e., interconnects)

438/622 ...Multiple metal levels, separated by
insulating layer (i.e., multiple level metallization)

2 700/121 (1 OR, 1 XR)

Class 700 : DATA PROCESSING: GENERIC CONTROL SYSTEMS OR
SPECIFIC APPLICATIONS

700/90 SPECIFIC APPLICATION, APPARATUS OR PROCESS

700/95 .Product assembly or manufacturing

700/117 ..Particular manufactured product or operation

700/121 ...Integrated circuit production or
semiconductor fabrication